

# ANTREX Electronics

Electronic Components Sourcing Information

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## Product Reference Information

**Part Number:** V40DM153C-M3/I  
**Manufacturer:** Vishay General Semiconductor - Diodes Division  
**Package:** Tape & Reel (TR)  
**Availability:** Please confirm with sales

### Product Page:

<https://antrexco.com/product/details/vishay-general-semiconductor-diodes-division/v40dm153c-m3-i.html>



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## Quality & Trust

New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

### Note:

This PDF includes an ANTREX product reference cover page.

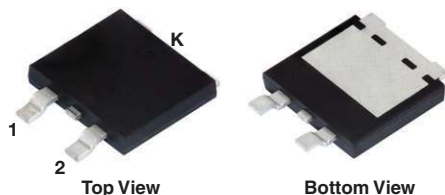
The original manufacturer datasheet follows from the next page.

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# Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.52 \text{ V}$  at  $I_F = 5.0 \text{ A}$

## eSMP® Series SMPD (TO-263AC)



## FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## LINKS TO ADDITIONAL RESOURCES



## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

## PRIMARY CHARACTERISTICS

|                                                          |                 |
|----------------------------------------------------------|-----------------|
| $I_{F(AV)}$                                              | 2 x 20 A        |
| $V_{RRM}$                                                | 150 V           |
| $I_{FSM}$                                                | 160 A           |
| $V_F$ at $I_F = 20 \text{ A}$ ( $T_J = 125 \text{ °C}$ ) | 0.69 V          |
| $T_J$ max.                                               | 175 °C          |
| Package                                                  | SMPD (TO-263AC) |
| Circuit configuration                                    | Common cathode  |

## MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

## MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

| PARAMETER                                                                          | SYMBOL            | V40DM153C   | UNIT |
|------------------------------------------------------------------------------------|-------------------|-------------|------|
| Device marking code                                                                |                   | V40DM153C   |      |
| Maximum repetitive peak reverse voltage                                            | $V_{RRM}$         | 150         | V    |
| Maximum average forward rectified current<br>(fig. 1)                              | $I_{F(AV)}^{(1)}$ | 40<br>20    | A    |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$         | 160         | A    |
| Operating junction temperature range                                               | $T_J^{(2)}$       | -40 to +175 | °C   |
| Storage temperature range                                                          | $T_{STG}$         | -55 to +175 |      |

## Notes

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                                         | TEST CONDITIONS        |                         | SYMBOL                        | TYP.  | MAX. | UNIT |
|---------------------------------------------------|------------------------|-------------------------|-------------------------------|-------|------|------|
| Instantaneous forward voltage per diode           | I <sub>F</sub> = 5 A   | T <sub>J</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.64  | -    | V    |
|                                                   | I <sub>F</sub> = 10 A  |                         |                               | 0.76  | -    |      |
|                                                   | I <sub>F</sub> = 20 A  |                         |                               | 0.94  | 1.12 |      |
|                                                   | I <sub>F</sub> = 5 A   | T <sub>J</sub> = 125 °C |                               | 0.52  | -    |      |
|                                                   | I <sub>F</sub> = 10 A  |                         |                               | 0.60  | -    |      |
|                                                   | I <sub>F</sub> = 20 A  |                         |                               | 0.69  | 0.74 |      |
| Reverse current at rated V <sub>R</sub> per diode | V <sub>R</sub> = 100 V | T <sub>J</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | 0.001 | -    | mA   |
|                                                   |                        | T <sub>J</sub> = 125 °C |                               | 1.5   | -    |      |
|                                                   | V <sub>R</sub> = 150 V | T <sub>J</sub> = 25 °C  |                               | -     | 0.15 |      |
|                                                   |                        | T <sub>J</sub> = 125 °C |                               | 4     | 12   |      |
| Typical junction capacitance                      | 4.0 V, 1 MHz           |                         | C <sub>J</sub>                | 800   | -    | pF   |

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                             | SYMBOL                   | V40DM153C | UNIT                 |
|---------------------------------------|--------------------------|-----------|----------------------|
| Typical thermal resistance per device | $R_{\theta JC}^{(1)}$    | 1.6       | $^{\circ}\text{C/W}$ |
|                                       | $R_{\theta JA}^{(2)(3)}$ | 58        |                      |

**Notes**

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-ambient

(3) Free air, without heatsink

**ORDERING INFORMATION** (Example)

| PREFERRED P/N                 | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
|-------------------------------|-----------------|--------------|---------------|------------------------------------|
| V40DM153C-M3/I                | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |
| V40DM153CHM3/I <sup>(1)</sup> | 0.55            | I            | 2000/reel     | 13" diameter plastic tape and reel |

**Note**

(1) AEC-Q101 qualified

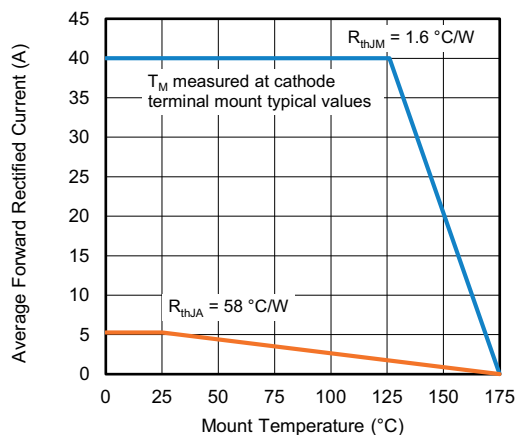
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

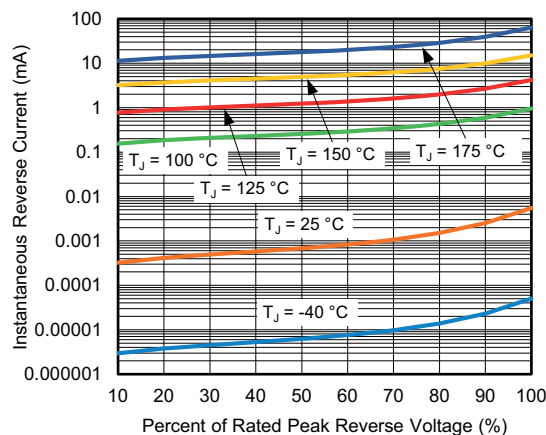


Fig. 4 - Typical Reverse Leakage Characteristics

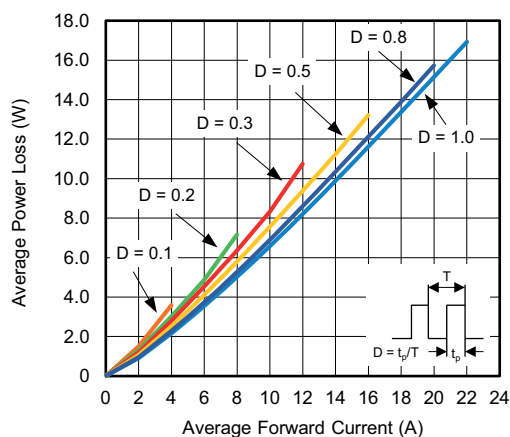


Fig. 2 - Average Power Loss Characteristics

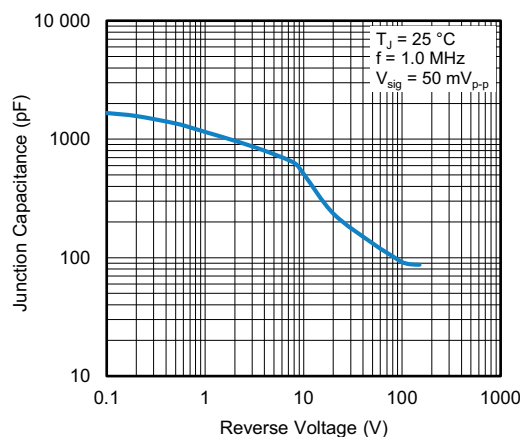


Fig. 5 - Typical Junction Capacitance

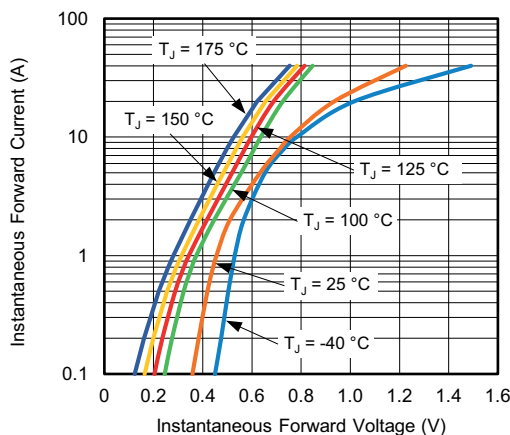


Fig. 3 - Typical Instantaneous Forward Characteristics

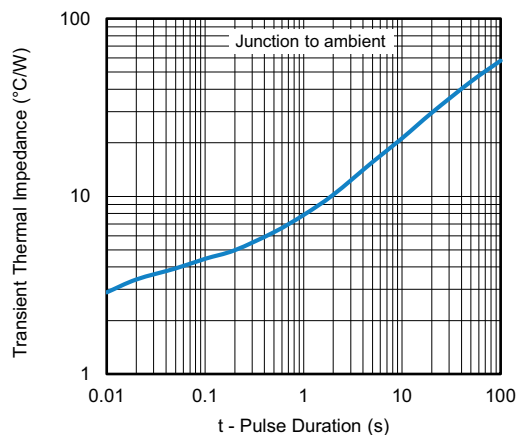


Fig. 6 - Typical Transient Thermal Impedance

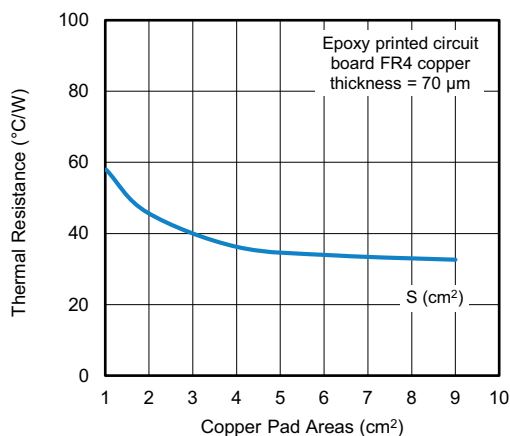
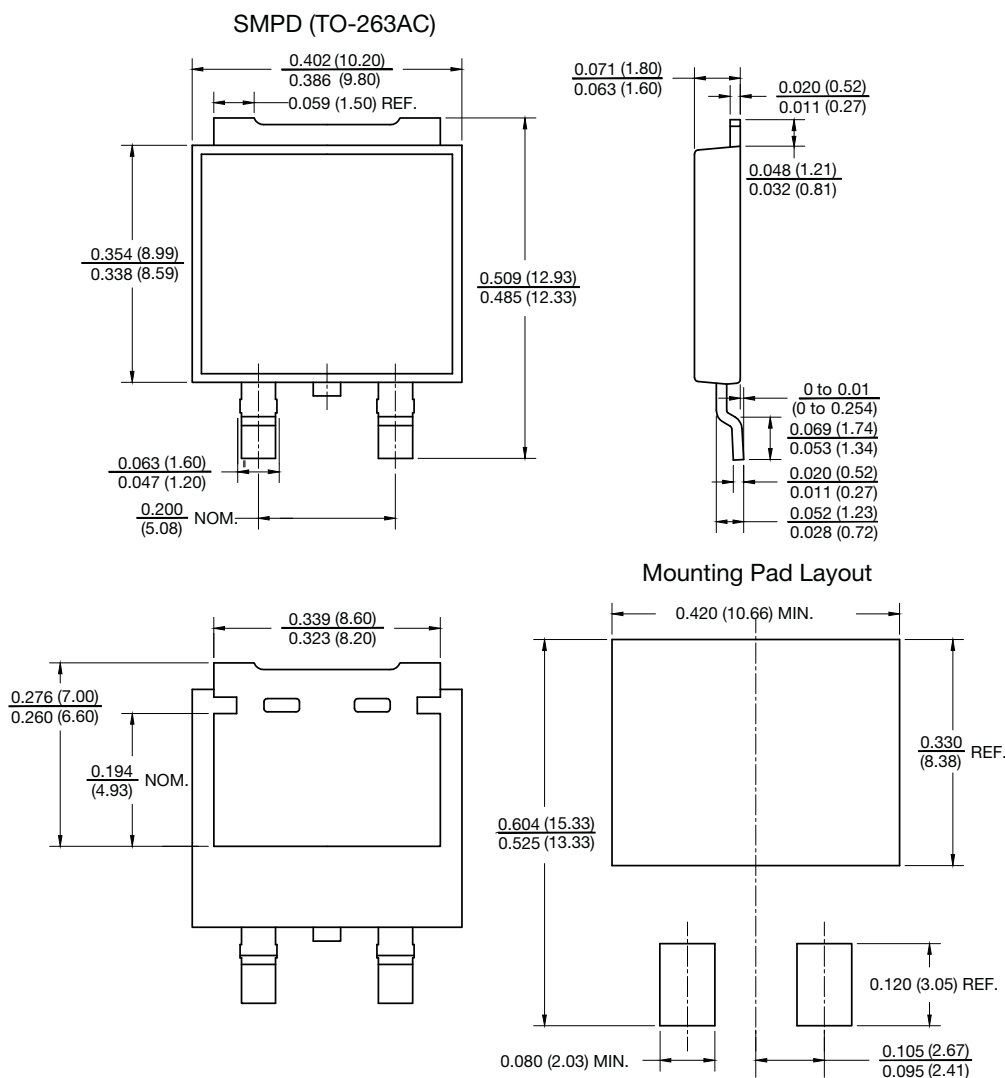


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)




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